

ABSTRACT OF THE DISCLOSURE

A semiconductor device includes a substrate, a semiconductor chip mounted on one surface of the substrate, wherein the semiconductor chip has an integrated circuit and bonding pads formed on a main surface thereof. The main surface of the semiconductor chip has a quadrilateral shape with the bonding pads being disposed along four sides of the main surface. A plurality of conductors is disposed on the one surface of the substrate so as to surround the semiconductor chip along four sides thereof and a plurality of bonding wires electrically connect the bonding pads with tips of the conductors, respectively. A resin body seals the semiconductor chip, the conductors and the plurality of bonding wires. A pitch between adjacent bonding pads increases in a direction toward four corners defined by the four sides of the main surface of the semiconductor chip.